

# 650V N-Channel Silicon Carbide Power MOSFET

## FEATURES

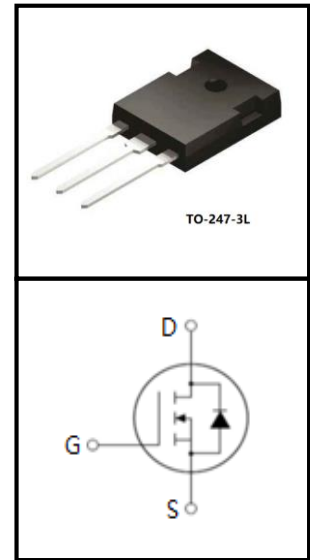
- Low On-Resistance
- Low Capacitance
- Avalanche Ruggedness
- Halogen Free, RoHS Compliant

## BENEFITS

- Higher System Efficiency
- Parallel Device Convenience
- High Temperature Application
- High Frequency Operation

## APPLICATIONS

- Switch Mode Power Supply (SMPS)
- Power Factor Correction (PFC)
- Uninterruptible Power Supply (UPS)
- EV Charging station & Motor Drives
- Solar/ Wind Renewable Energy
- Power Inverters & DC/DC Converters



Device Marking and Package Information		
Device	Package	Marking
C2M065W030	TO-247-3L	C2M065W030

Absolute Maximum Ratings $T_C = 25^\circ\text{C}$ , unless otherwise noted				
Parameter	Symbol	Test Conditions	Value	Unit
Drain-Source Voltage	$V_{DSS}$	$V_{GS}=0V, I_{DS}=100\mu A$	650	V
Continuous Drain Current	$I_D$	$V_{GS}=20V, T_C=25^\circ C$	100	A
Pulsed Drain Current	$I_{DM}$	$t_{PW}$ limitation per Fig.17	400	
Power Dissipation	$P_D$	$T_C=25^\circ C$	338	W
Recommend Gate Source Voltage	$V_{GS, op}$	Static	-5/+20	V
Maximum Gate Source Voltage	$V_{GS, max}$	AC ( $f > 1\text{Hz}$ )	-10/+25	
Soldering Temperature	$T_L$		260	$^\circ\text{C}$
Operating Junction and Storage Temperature Range	$T_J, T_{stg}$		-55/+150	

Thermal Resistance			
Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case	$R_{thJC}$	0.37	K/W

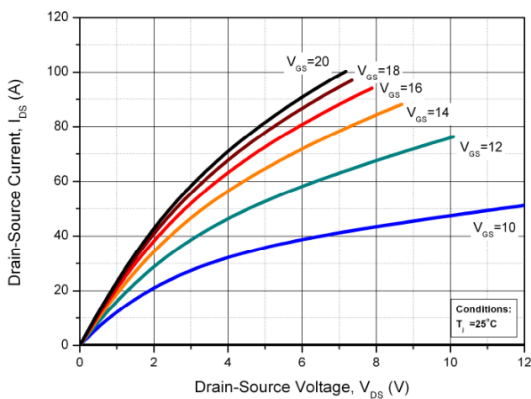
**Specifications**  $T_J = 25^{\circ}\text{C}$ , unless otherwise noted

Parameter	Symbol	Test Conditions	Value			Unit
			Min.	Typ.	Max.	
<b>Static</b>						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = 100\mu A$	650	--	--	V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = 650V, V_{GS} = 0V, T_J = 25^{\circ}\text{C}$	--	<1	100	$\mu A$
		$V_{DS} = 650V, V_{GS} = 0V, T_J = 150^{\circ}\text{C}$	--	10	500	
Gate-Source Leakage	$I_{GSS}$	$V_{GS} = 20V, V_{DS} = 0V$	--	--	200	nA
Gate-Source Threshold Voltage	$V_{GS(th)}$	$V_{DS} = 10V, I_D = 5mA$	2	--	3.5	V
Drain-Source On-Resistance	$R_{DS(on)}$	$V_{GS} = 20V, I_D = 30A$	--	30	36	m $\Omega$
<b>Dynamic</b>						
Input Capacitance	$C_{iss}$	$V_{GS} = 0V$ $V_{DS} = 400V$ $f = 1.0MHz$ $V_{AC} = 25mV$	--	2333	--	$\mu F$
Output Capacitance	$C_{oss}$		--	264	--	
Reverse Transfer Capacitance	$C_{rss}$		--	46	--	
Effective Output Capacitance, Energy Related	$C_{o(er)}$		$V_{GS} = 0V$ $V_{DS} = 0$ to 450V		187	
Effective Output Capacitance, Time Related	$C_{o(tr)}$	$I_D = \text{const.}, V_{GS} = 0V$ $V_{DS} = 0$ to 450V		253		
Total Gate Charge	$Q_g$	$V_{DS} = 300V,$ $V_{GS} = 0/+15V,$ $I_D = 50A$	--	140	--	nC
Gate-Source Charge	$Q_{gs}$		--	26	--	
Gate-Drain Charge	$Q_{gd}$		--	69	--	
Gate plateau voltage	$V_{pl}$		--	10	--	
Turn-on Delay Time	$t_{d(on)}$	$V_{DS} = 300V$ $V_{GS} = 0/15V$ $I_D = 50A$ $R_{G(ext)} = 2.5\Omega$	--	45	--	ns
Turn-on Rise Time	$t_r$		--	107	--	
Turn-off Delay Time	$t_{d(off)}$		--	67	--	
Turn-off Fall Time	$t_f$		--	16	--	
Coss Stored Energy	$E_{oss}$	$V_{GS} = 0V, V_{DS} = 650V$ $f = 1MHz, V_{AC} = 25mV$	--	119	--	$\mu J$
Turn-on Switching Energy	$E_{on}$	$V_{DS} = 650V,$ $V_{GS} = 0/15V, I_D = 20A,$ $R_{G(ext)} = 2.5\Omega$	--	194*	--	
Turn-off Switching Energy	$E_{off}$		--	326*	--	
Internal Gate Resistance	$R_{G(int.)}$	$f = 1MHz, V_{AC} = 25mV$	--	3	--	$\Omega$

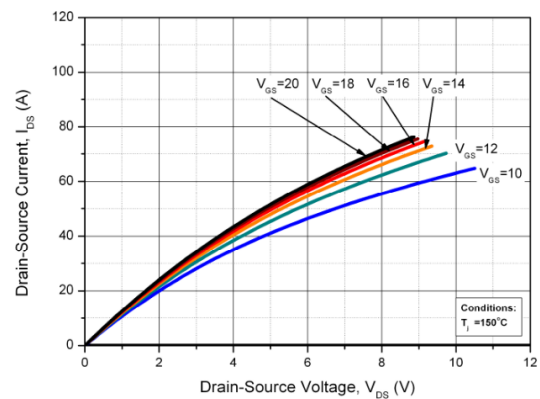
\*Base on the results of calculation, note that the energy loss caused by the reverse recovery of FWD is not included in  $E_{on}$ .

Built-in SiC Diode Characteristics						
Continuous Diode Forward Current	$I_S$	$V_{GS} = 0V$	--	100	--	A
Inverse Diode Forward Voltage	$V_{SD}$	$I_{SD} = 30A, V_{GS} = -5V$	--	--	6	V
Reverse Recovery Time	$t_{rr}$	$I_F = 25A, V_{DS}=150V, di_F/dt = 500A/\mu s$	--	72	--	ns
Reverse Recovery Charge	$Q_{rr}$		--	181	--	nC
Peak Reverse Recovery Current	IRM		--	4.6	--	A

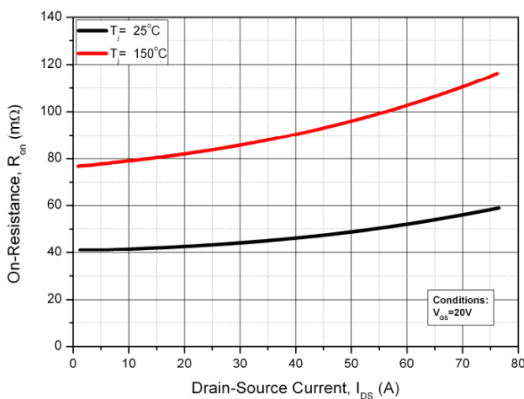
**Typical Device Performance**



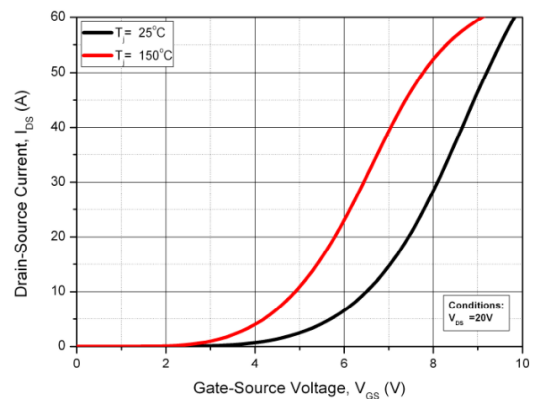
**Fig. 1 Forward Output Characteristics at  $T_j = 25^\circ C$**



**Fig. 2 Forward Output Characteristics at  $T_j = 150^\circ C$**



**Fig. 3 On-Resistance vs. Drain Current for Various  $T_j$**



**Fig. 4 Transfer Characteristics for Various  $T_j$**

Typical Device Performance

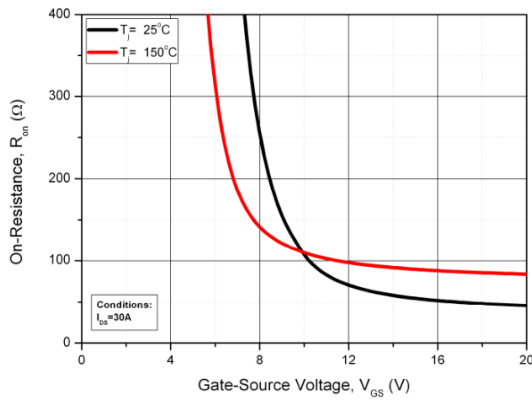


Fig. 5 On-Resistance vs. Gate Voltage for Various  $T_j$

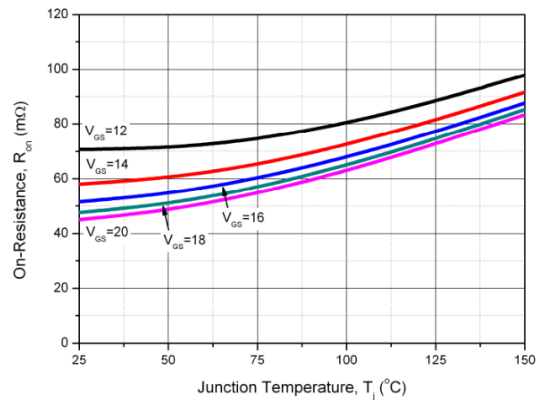


Fig. 6 On-Resistance vs. Temperature for Various Gate Voltage

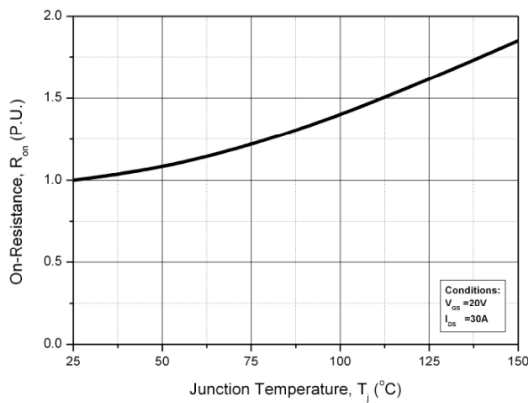


Fig. 7 Normalized On-Resistance vs. Temperature

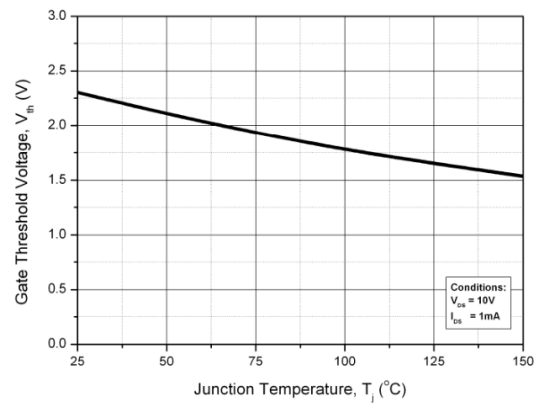


Fig. 8 Threshold Voltage vs. Temperature

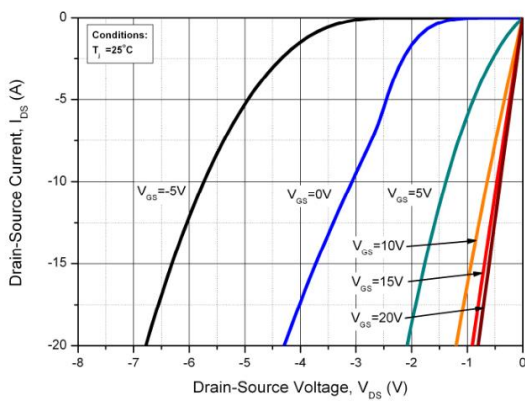


Fig. 9 Reverse Output Characteristics at  $T_j = 25^\circ\text{C}$

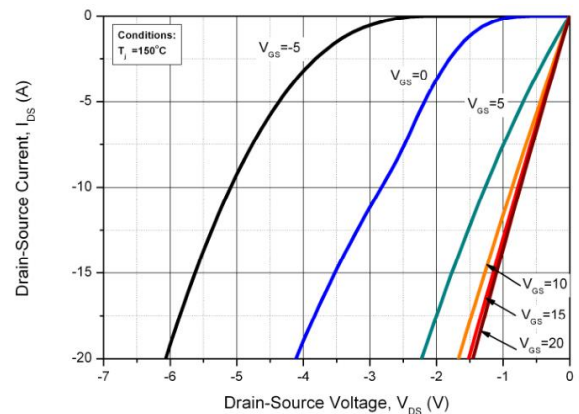


Fig. 10 Reverse Output Characteristics at  $T_j = 150^\circ\text{C}$

Typical Device Performance

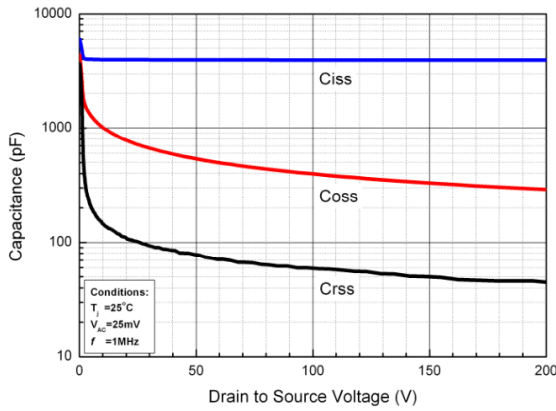


Fig. 11 Capacitances vs. Drain to Source Voltage (0 - 200V)

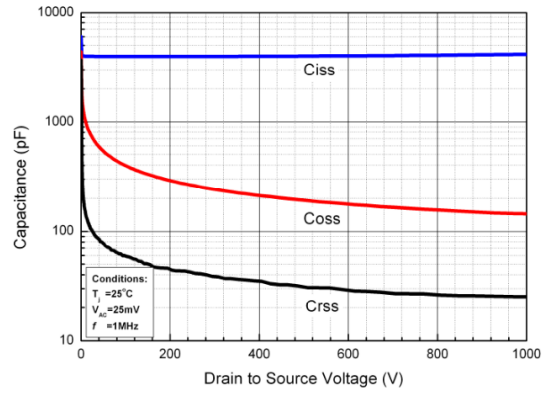


Fig. 12 Capacitances vs. Drain to Source Voltage (0 - 1000V)

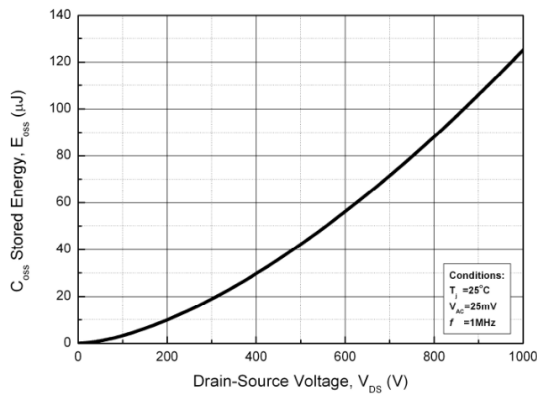


Fig. 13 Output Capacitor Stored Energy

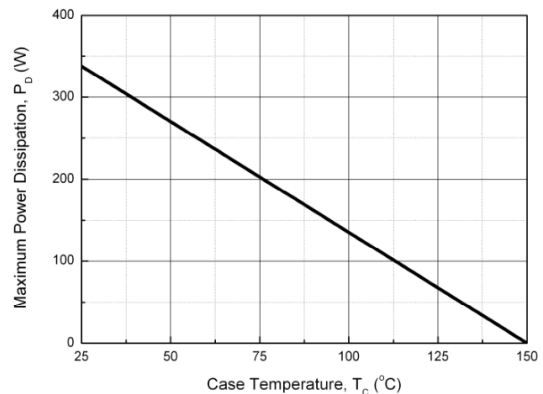


Fig. 14 Maximum Power Dissipation Derating vs. Case Temperature

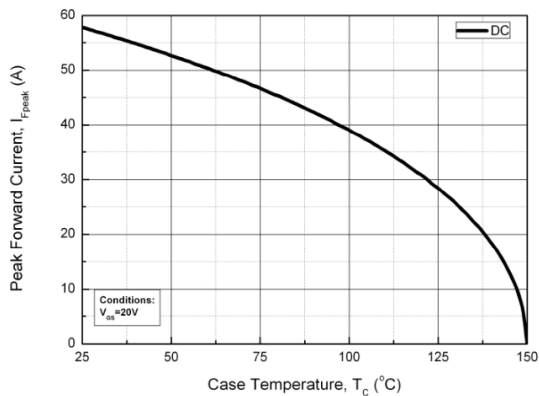


Fig. 15 Drain Current Derating vs. Case Temperature

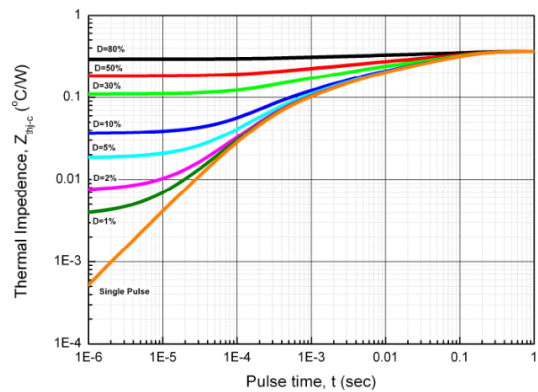
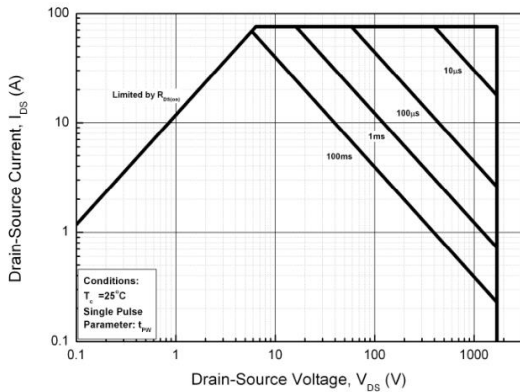
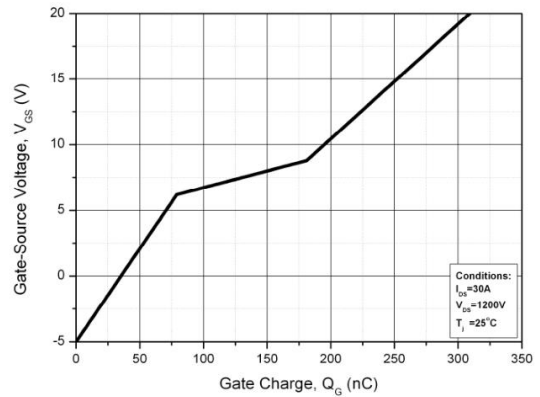
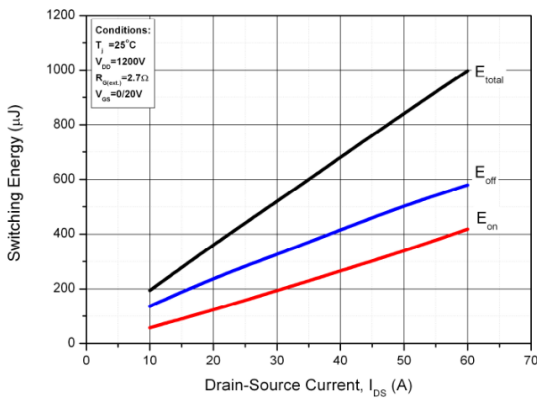
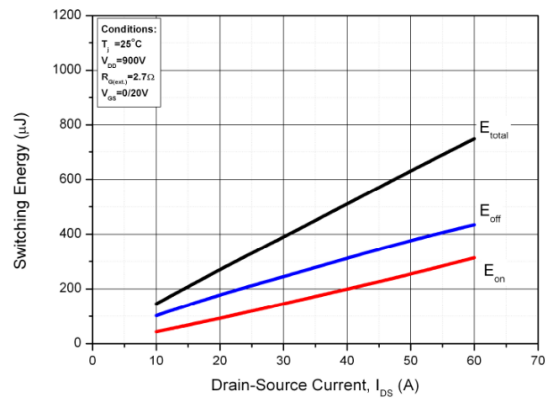
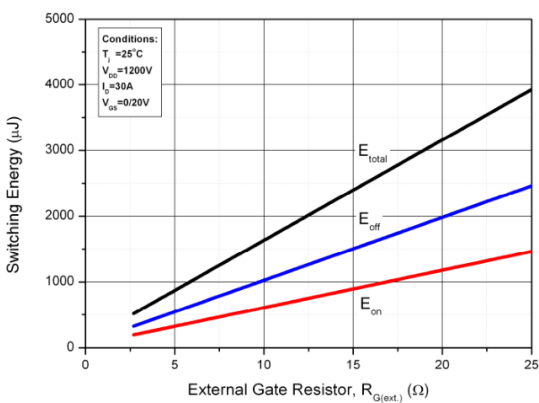
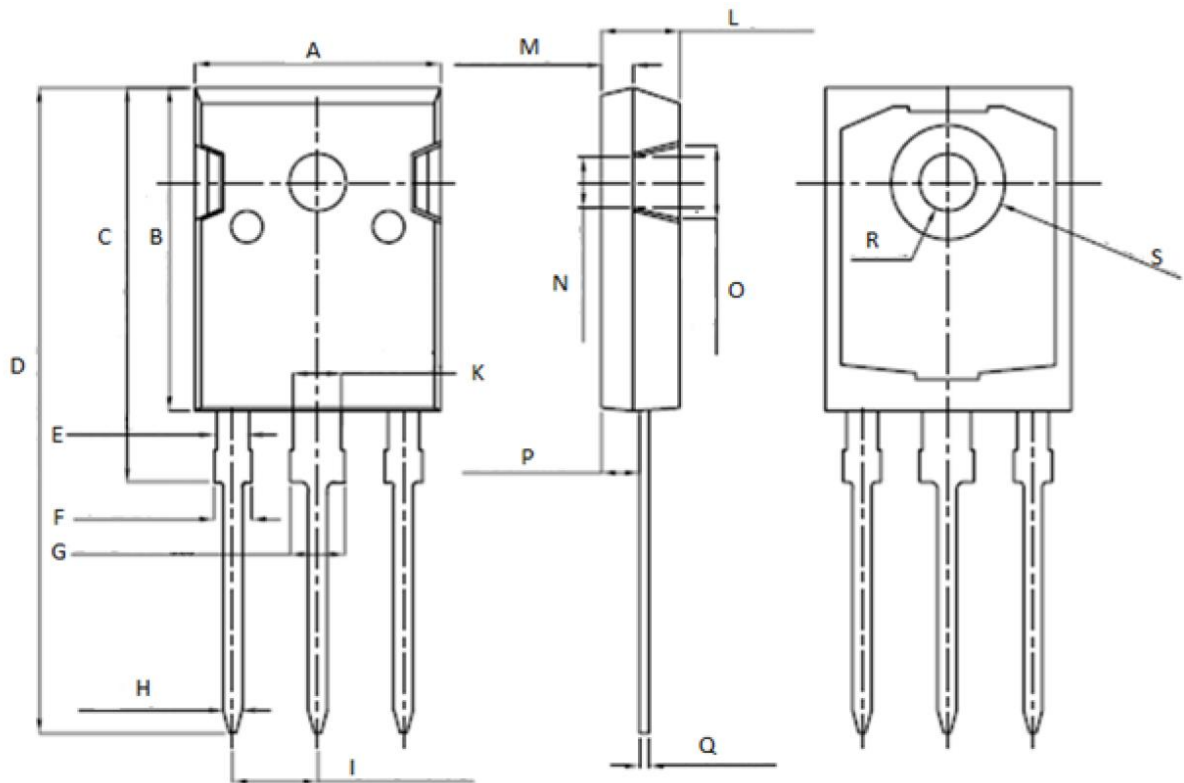


Fig. 16 Transient Junction to Case Thermal Impedance

**Typical Device Performance**

**Fig. 17 Safe Operating Area**

**Fig. 18 Gate Charge Characteristics**

**Fig. 19 Clamped Inductive Switching Energy vs. Drain Current ( $V_{DD} = 1200\text{V}$ )\***

**Fig. 20 Clamped Inductive Switching Energy vs. Drain Current ( $V_{DD} = 900\text{V}$ )\***

**Fig. 21 Clamped Inductive Switching Energy vs. External Gate Resistor ( $R_{G(ext.)}$ )\***

\*Base on the results of calculation, note that the energy loss caused by the reverse recovery of FWD is not included in  $E_{on}$ .

**TO-247**


Unit: mm		
Symbol	Min.	Max.
A	15.95	16.25
B	20.85	21.25
C	20.95	21.35
D	40.5	40.9
E	1.9	2.1
F	2.1	2.25
G	3.1	3.25
H	1.1	1.3
I	5.40	5.50

Unit: mm		
Symbol	Min.	Max.
K	2.90	3.10
L	4.90	5.30
M	1.90	2.10
N	4.50	4.70
O	5.40	5.60
P	2.29	2.49
Q	0.51	0.71
R	φ 3.5	φ 3.7
S	φ 7.1	φ 7.3

\*The information provided herein is subject to change without notice.

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